

## TIDEP0084: Sub-1 GHz Sensor to Cloud Industrial Internet of Things (IoT) Gateway Reference Design

## Texas Instruments - BBB-LP-ADAPTER BOM

Rev A

Date September 28, 2016

## DNP - Indicates Do Not Populate

Item Number	Description	Manufacturer	MPN	Part Reference	Value	Quantity	Notes/ Alternatives
1	CONNECTOR, HEADER, MALE, STRAIGHT, 2 ROWS, 46 PINS, PITCH 2.54mm, PTH	TE CONNECTIVITY	2-87215-3	J8 J9	2-87215-3	2	Bottom Mount, LONG PINS should be on the Bottom side of the PCB.
2	CONNECTOR, HEADER, MALE, STRAIGHT, 1 ROW, 3 PINS, PITCH 2.54mm, PTH	TE CONNECTIVITY	87224-3	J10	87224-3	1	
3	CONNECTOR, HEADER, MALE, STRAIGHT, 1 ROW, 2 PINS, PITCH 2.54mm, PTH	TE CONNECTIVITY	87224-2	J11	87224-2	1	
4	MECHANIC, SHUNT, CURRENT RATING 4.3A PER PIN, 2.54 X 5.08 X 6.1mm, BLACK	SULLINS CONNECTOR	SPC02SYAN	M1 M2	SPC02SYAN	2	See Schematic for M1 and M2 Default positions
5	CONNECTOR, HEADER, MALE, STRAIGHT, 2 ROWS, 20 PINS, PITCH 2.54mm, PTH	SAMTEC	SSW-110-23-F-D	P1 P2	SSW-110-23-F-D	2	Bottom Mount, PINS should protrude to the top side of the PCB
6	RESISTOR, THICK FILM, 0, 0.1W, 50V, -55DEGC/+155DEGC, 0402, SMD	PANASONIC INDUSTRIAL	ERJ2GE0R00X	R1-R15, R17-R23	0	22	
7	RESISTOR, THICK FILM, 0, 0.1W, 50V, -55DEGC/+155DEGC, 0402, SMD	PANASONIC INDUSTRIAL	ERJ2GE0R00X	R16	DNP	0	
8	FIDUCIAL MARK, ROUND 1MM			FIDU1 FIDU2 FIDU3	FIDU_1MM	0	PCB Drafting item
9	PCB, 2-Layer, FR4, 3.4"*2.15", 1.6mm thickness, 1Oz Copper					1	
LaunchPad and BeagleBone Black Boards Used in this TI Design							
1	Simplelink™ Sub-1 GHz and Bluetooth® low energy CC1350 wireless MCU LaunchPad™ Development Kit	TI	LAUNCHXL-CC1350			1	<a href="http://www.ti.com/tool/launchxl-cc1350">http://www.ti.com/tool/launchxl-cc1350</a>
2	BeagleBone Black Development Board	BB	BEAGLEBK			1	<a href="#">BEAGLEBK</a>

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